

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 25, 2003

For: HIGH DENSITY CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE

**RESPONSE UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action, dated March 6, 2006, please consider the following  
Remarks.